L	Hits	Search Text	DB	Time stamp
Number 1	1	6066030.pn.	USPAT	2003/12/01
_				10:08
_	27241	(cmp or polish or polished or polishing	USPAT	2003/12/01
		or planarizing or planarize) and (cu or		10:08
_	1068	copper) ((cmp or polish or polished or polishing	USPAT	2003/11/05
	1000	or planarizing or planarize) and (cu or	001111	14:27
		copper)) and (chelate or chelating)		İ
-	255	(((cmp or polish or polished or polishing	USPAT	2003/11/05
		or planarizing or planarize) and (cu or copper)) and (chelate or chelating)) and		13:16
		(cathode or anode or electrolytic or		
		electrolyze)		
_	251	((((cmp or polish or polished or	USPAT	2003/11/05
		polishing or planarizing or planarize)		13:17
		and (cu or copper)) and (chelate or chelating)) and (cathode or anode or		
	1	electrolytic or electrolyze)) and		
		@ay<=2001		
_	228	((((cmp or polish or polished or	USPAT	2003/11/05
		polishing or planarizing or planarize) and (cu or copper)) and (chelate or		15:11
		chelating)) and (cathode or anode or		
		electrolytic or electrolyze)) and		
		@ay<=2000		
_	17	(((((cmp or polish or polished or polishing or planarizing or planarize)	USPAT	2003/11/05
		and (cu or copper)) and (chelate or		13:30
		chelating)) and (cathode or anode or		
		electrolytic or electrolyze)) and		
		@ay<=2000) and (cmp or polish or polished		
		or polishing or planarizing or planarize).ab.		
_	159	(((cmp or polish or polished or polishing	USPAT	2003/11/05
		or planarizing or planarize) and (cu or		13:38
		copper)) and (chelate or chelating)) and		
		(cmp or polish or polished or polishing or planarizing or planarize).ab.		
-	128	((((cmp or polish or polished or	USPAT	2003/11/05
		polishing or planarizing or planarize)		13:38
		and (cu or copper)) and (chelate or		
		chelating)) and (cmp or polish or polished or polishing or planarizing or		
		planarize).ab.) and @aY<=2000		
	950	(((cmp or polish or polished or polishing	USPAT	2003/11/05
		or planarizing or planarize) and (cu or		14:27
		copper)) and (chelate or chelating)) and @ay<=2000		
_	108	((((cmp or polish or polished or	USPAT	2003/11/05
		polishing or planarizing or planarize)		14:27
		and (cu or copper)) and (chelate or		
_	87	chelating)) and @ay<=2000) and shear (((((cmp or polish or polished or	USPAT	2003/11/05
		polishing or planarizing or planarize)		14:28
		and (cu or copper)) and (chelate or		
		chelating)) and @ay<=2000) and shear) not		
		<pre>(((((cmp or polish or polished or polishing or planarizing or planarize)</pre>		
		and (cu or copper)) and (chelate or		
İ		chelating)) and (cmp or polish or		
		polished or polishing or planarizing or		
	L	planarize).ab.) and @aY<=2000)	l	

_	211	(((((cmp or polish or polished or polishing or planarizing or planarize) and (cu or copper)) and (chelate or	USPAT	2003/11/05 15:11
	<u> </u>	chelating)) and (cathode or anode or electrolytic or electrolyze)) and (@ay<=2000) not (((cmp or polish or		
		polished or polishing or planarizing or planarize) and (cu or copper)) and		
		(chelate or chelating)) and (cmp or polish or polished or polishing or		
_	198	planarizing or planarize).ab.) (((((cmp or polish or polished or	USPAT	2003/11/05
		polishing or planarizing or planarize) and (cu or copper)) and (chelate or		15:11
		chelating)) and (cathode or anode or electrolytic or electrolyze)) and		
		@ay<=2000) not ((((cmp or polish or polished or polishing or planarizing or planarize) and (cu or copper)) and		
		(chelate or chelating)) and (cmp or polish or polished or polishing or		
		planarizing or planarize).ab.)) not (((((cmp or polish or polished or		
		polishing or planarizing or planarize) and (cu or copper)) and (chelate or		
		chelating)) and @ay<=2000) and shear) not ((((cmp or polish or polished or		
		polishing or planarizing or planarize) and (cu or copper)) and (chelate or chelating)) and (cmp or polish or		
		polished or polishing or planarizing or planarize).ab.) and @aY<=2000))		
_	9767	((cmp or polish or polished or polishing or planarizing or planarize) and (cu or	USPAT	2003/11/05 15:45
_	889	copper)) and parallel ((cmp or polishing	USPAT	2003/11/05
		or planarizing or planarize) and (cu or copper)) and ((flow or flowing or jet or solution or slurry) with parallel)		15:46
-	54	(((cmp or polish or polished or polishing or planarizing or planarize) and (cu or	USPAT	2003/11/05 15:46
		copper)) and ((flow or flowing or jet or solution or slurry) with parallel)) and		
_	27241	(chelate or chelating or ligand) (cmp or polish or polished or polishing	USPAT	2003/11/06
	0211	or planarizing or planarize) and (cu or copper)	исраш	10:33
	8211	((cmp or polish or polished or polishing or planarizing or planarize) and (cu or copper)) and (groove or (contact adj	USPAT	2003/11/06
_	1247	hole) or inter\$1connection) (((cmp or polish or polished or polishing	USPAT	2003/11/06
		or planarizing or planarize) and (cu or copper)) and (groove or (contact adj		09:32
	1322	hole) or inter\$1connection)) and slurry (((cmp or polish or polished or polishing	USPAT	2003/11/06
		or planarizing or planarize) and (cu or copper)) and (groove or (contact adj hole) or inter\$lconnection)) and (slurry		09:32
_	1247	or (polish\$3 near3 solution)) ((((cmp or polish or polished or	USPAT	2003/11/06
		polishing or planarizing or planarize) and (cu or copper)) and (groove or		09:33
		(contact adj hole) or inter\$1connection)) and slurry) and (slurry or (polish\$3		
_	7514	near3 solution)) (cmp or polish or polished or polishing or planarizing or planarize) same (cu or	USPAT	2003/11/06 09:34
		copper)		

				
-	684	((((cmp or polish or polished or	USPAT	2003/11/06
		polishing or planarizing or planarize)		09:35
		and (cu or copper)) and (groove or		
	1	(contact adj hole) or inter\$1connection))		
		and slurry) and (slurry or (polish\$3		
		near3 solution))) and ((cmp or polish or		
		polished or polishing or planarizing or	1	
	5.50	planarize) same (cu or copper))		
_	571	(((((cmp or polish or polished or	USPAT	2003/11/06
		polishing or planarizing or planarize)		09:35
		and (cu or copper)) and (groove or	<u> </u>	
		(contact adj hole) or inter\$1connection))		1
		and slurry) and (slurry or (polish\$3		
		near3 solution))) and ((cmp or polish or polished or polishing or planarizing or		
		planarize) same (cu or copper))) and		
	1	Gay<=2000		
	150	((((((cmp or polish or polished or	USPAT	2003/11/06
	150	polishing or planarizing or planarize)	ODEAL	09:36
		and (cu or copper)) and (groove or		09.30
		(contact adj hole) or inter\$1connection))		
		and slurry) and (slurry or (polish\$3		
		near3 solution))) and ((cmp or polish or		
		polished or polishing or planarizing or		
		planarize) same (cu or copper))) and		
		@ay<=2000) and (chelate or chelating or	İ	
ĺ		additive or ligand)		
_	884	(cmp or polish or polished or polishing	USPAT	2003/11/06
		or planarizing or planarize) and (shear		10:43
		adj stress)		
-	316	((cmp or polish or polished or polishing	USPAT	2003/11/06
		or planarizing or planarize) and (shear		10:33
	200	adj stress)) and (copper or Cu)		2222 (11 (25
-	299	(((cmp or polish or polished or polishing	USPAT	2003/11/06
		or planarizing or planarize) and (shear		10:33
		adj stress)) and (copper or Cu)) and		
_	298	@ay<=2000 ((((cmp or polish or polished or	USPAT	2003/11/06
	230	t(((cmp of polish of polished of polishing or planarize)	USPAI	10:34
		and (shear adj stress)) and (copper or		10.54
		Cu)) and @ay<=2000) not ((((((cmp or		
		polish or polished or polishing or		
		planarizing or planarize) and (cu or		
		copper)) and (groove or (contact adj		
		hole) or inter\$1connection)) and slurry)		
		and (slurry or (polish\$3 near3	İ	
	j i	solution))) and ((cmp or polish or		
		polished or polishing or planarizing or		<u> </u>
		planarize) same (cu or copper))) and		
		<pre>@ay<=2000) and (chelate or chelating or</pre>		
		additive or ligand))		0000/44/55
-	121	(cmp or polish or polished or polishing	USPAT	2003/11/06
		or planarizing or planarize) same (shear		10:35
	111	adj stress)	114575	2002/11/06
-	114	((cmp or polish or polished or polishing	USPAT	2003/11/06
		or planarizing or planarize) same (shear adj stress)) and @ay<=2000		10:36
_	114	adj stress);	USPAT	2003/11/06
	114	or planarizing or planarize) same (shear	USPAI	10:36
		adj stress)) and @ay<=2000) not		
		(((((((cmp or polish or polished or		
		polishing or planarizing or planarize)		
		and (cu or copper)) and (groove or		
]		(contact adj hole) or inter\$1connection))		
		and slurry) and (slurry or (polish\$3		
		near3 solution))) and ((cmp or polish or		
[polished or polishing or planarizing or		
		planarize) same (cu or copper))) and		
		@ay<=2000) and (chelate or chelating or		
		additive or ligand))	l	<u> </u>

_	251	(cmp or polish or polished or polishing	US-PGPUB;	2003/11/06
		or planarizing or planarize) and (shear	EPO; JPO;	10:43
		adj stress)	DERWENT	
_	42	' '	US-PGPUB;	2003/11/06
		or planarizing or planarize) and (shear	EPO; JPO;	10:44
		adj stress)) and @ay<=2000	DERWENT	
_	7686	(cmp or polish or polished or polishing	USPAT	2003/11/26
		or planarizing or planarize or		16:37
		electro\$1polish or electro\$1polishing)		
		same (cu or copper)		
_	991	((cmp or polish or polished or polishing	USPAT	2003/11/26
		or planarizing or planarize or		16:38
		electro\$1polish or electro\$1polishing)		
	İ	same (cu or copper)) and cathode		
	688	(((cmp or polish or polished or polishing	USPAT	2003/11/26
		or planarizing or planarize or	1	16:38
		electro\$1polish or electro\$1polishing)		
		same (cu or copper)) and cathode) and		
		anode		
-	304	(((cmp or polish or polished or	USPAT	2003/11/26
İ		polishing or planarizing or planarize or		16:39
		electro\$1polish or electro\$1polishing)]	
		same (cu or copper)) and cathode) and		
		anode) and (electrolytic or electrolyze)		
_	275	((((cmp or polish or polished or	USPAT	2003/11/26
		polishing or planarizing or planarize or		16:39
		electro\$1polish or electro\$1polishing)		
		same (cu or copper)) and cathode) and		
		anode) and (electrolytic or electrolyze))		
		and @ay<=2000		
-	221	(((((cmp or polish or polished or	USPAT	2003/11/26
		polishing or planarizing or planarize or		16:47
		electro\$1polish or electro\$1polishing)		1011
		same (cu or copper)) and cathode) and		
		anode) and (electrolytic or electrolyze))		
	:	and @ay<=2000) and ((voltage or power or		
		current) with (cathode or anode))		
_	60	((((((cmp or polish or polished or	USPAT	2003/11/26
·		polishing or planarizing or planarize or	051711	16:51
		electro\$1polish or electro\$1polishing)		10.01
		same (cu or copper)) and cathode) and		
		anode) and (electrolytic or electrolyze))		
		and @ay<=2000) and ((voltage or power or		
		current) with (cathode or anode))) and		
		(electro\$1polish or electro\$1polishing)]
	529	(electro\$1polish or electro\$1polishing)	USPAT	2003/11/26
	"2"	and copper	ODEMI	16:51
_ !	566	(electro\$1polish or electro\$1polishing)	USPAT	2003/11/26
		and (copper or Cu)	OPENI	16:51
_	273		USPAT	2003/11/26
	2,3	and (copper or Cu)) and cathode	OBEAT	16:51
_	252	(((electro\$1polish or electro\$1polishing)	USPAT	2003/11/26
i	252	and (copper or Cu)) and cathode) and	OSPAI	
		@ay<=2000		16:51
_	192	((((electro\$1polish or	TIC DAM	2002/11/26
	122	electro\$1polishing) and (copper or Cu))	USPAT	2003/11/26
		and cathode) and @ay<=2000) not		16:52
		(((((((cmp or polish or polished or		
		polishing or planarizing or planarize or		
İ		electro\$1polish or electro\$1polishing)		
		same (cu or copper)) and cathode) and		
		anode) and (electrolytic or electrolyze))		
		and Gay<=2000) and ((voltage or power or		
İ	İ	current) with (cathode or anode))) and		
	L	(electro\$1polish or electro\$1polishing))		